



PRODUCT DATASHEET



- UV (390-400nm)



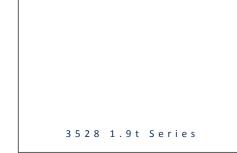
3528 1.9t Series



FEATURES:

- Package: PLCC2 White SMT Package
- Forward Current: 20mA
- Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 30mcd@20mA •
- Colour: Ultraviolet (UV) .
- Wavelength: 390-400nm
- Viewing angle: 120° •
- Materials:
 - Die: InGaN _
 - Resin: Silicon (Water Clear)
- Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- **Grouping parameters:**
 - Forward voltage _
 - Luminous intensity _
 - Peak wavelength _
- Soldering methods: Reflow Soldering
- Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with 2000/reel, ø180mm (7")

N0Q18S75



APPLICATIONS:

- Industrial Curing •
- Air Purifier •
- Poster Printing Curing •
- **Counterfeit Money Detector** •
- **Blood Detector** •
- Nail Curing

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Teeth Curing •



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	111	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

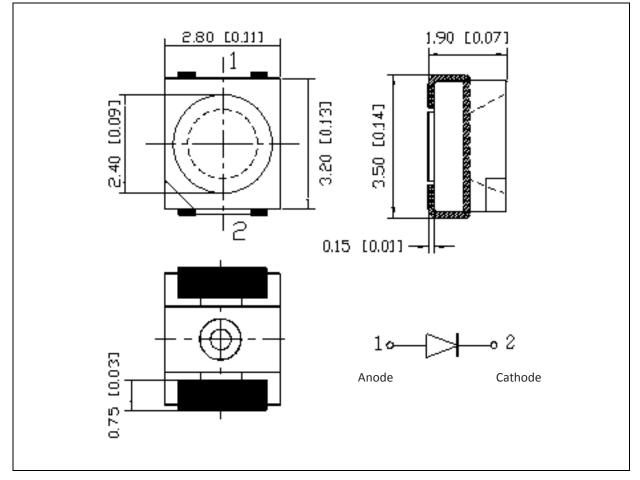
Parameter Symbol		Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Om	Condition
Forward Voltage	$V_{\rm F}$	2.8	3.2	3.7	V	I _F =20mA
Luminous Intensity	Iv	16	30	50	mcd	I _F =20mA
Dominant Wavelength	λ_{D}		445		nm	I _F =20mA
Peak Wavelength	λ_{P}	390	395	400	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		17		nm	I _F =20mA
Viewing Angle	20 _{1/2}		120		deg	I _F =20mA

 $1. \qquad \text{Luminous intensity (I_{V}) \pm 15\%, Forward Voltage (V_{F}) \pm 0.1V, Viewing angle(2\theta_{1/2}) \pm 5\%, Wavelength \pm 1nm.}$



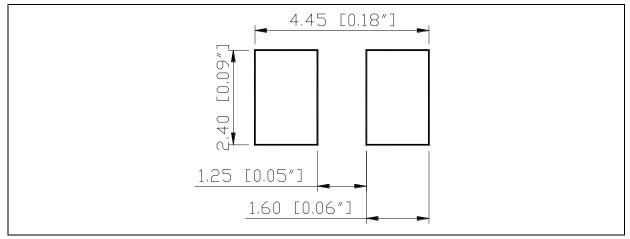
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



BINNING GROUPS:

Code	Min.	Max.	Unit
F	2.8	3.1	
G	3.1	3.4	V
Н	3.4	3.7	

Forward Voltage Classifications ($I_F = 20mA$):

Luminous Intensity Classifications (I_F = 20mA):

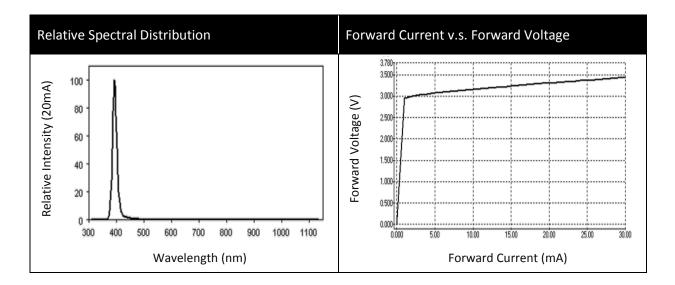
Code	Min.	Max.	Unit
С	16	20	
D	20	25	med
E	25	32	mcd
F	32	50	

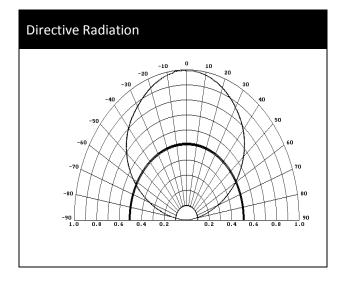
Dominant Wavelength Classifications ($I_F = 20mA$):

Code	Min.	Max.	Unit
E	390	395	2.22
F	395	400	nm



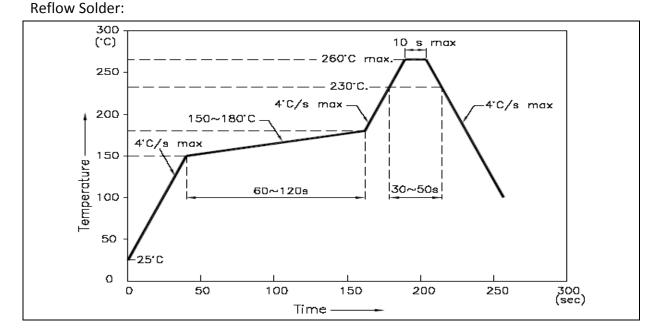
ELECTRO-OPTICAL CHARACTERISTICS:







RECOMMENDED SOLDERING PROFILE:



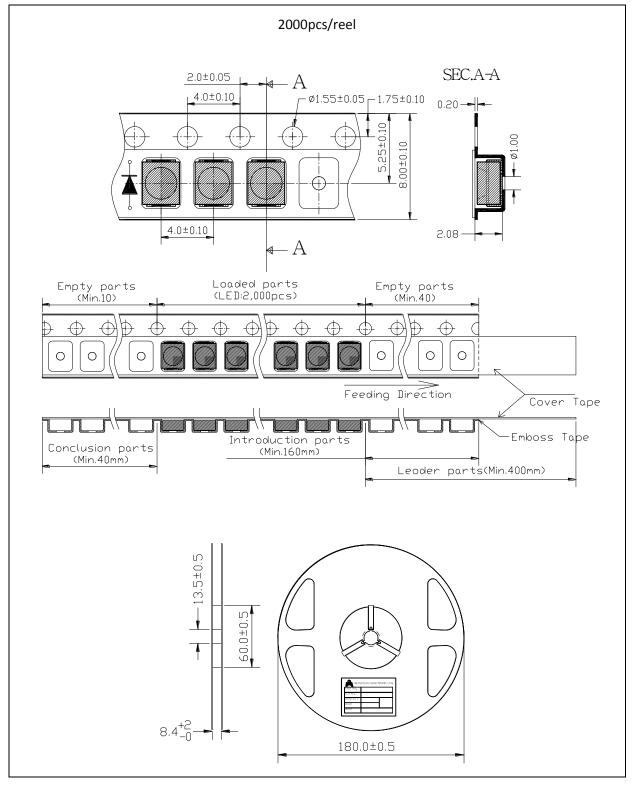
Note:

- 1. Recommend reflow temperature 245°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

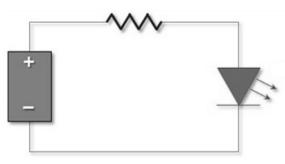
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 36hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	27/07/2015	Datasheet set-up.